STATE-OF-THE-ART SEMICONDUCTOR MANUFACTURING EQUIPMENT

2525 North 12th Street, Reading, Pennsylvania
(Approximately 60 Miles Northwest of Philadelphia)

WEDNESDAY & THURSDAY
NOVEMBER 13 & 14 AT 9:00 A.M.

BY ORDER OF AMERICAN ELECTRONIC COMPONENTS, INC. (AECI) REPRESENTING

Formerly Lucent Technologies Microelectronics Group

GoIndustry Group

http://www.michaelfox.com e-mail: info@michaelfox.com
DAVID S. FOX, PA. LIC. NO. AU-002273L, ROBERT D. SHERMAN, PA. LIC. NO. AU-002566L,
GILBERT SCHWARTZMAN, PA. LIC. NO. AU-002428-L

GoWebcast
www.michaelfox.com
WAFFER FABRICATION

PHOTOLITHOGRAPHY
- KARL SUSS MA150 Mask Aligner.
- KARL SUSS MA6 Mask Aligner.
- KARL SUSS RC8 Photore sist Coat/Bake Tool.
- C&D SEMICONDUCTOR 8832CTD/8836HPO 2-Track Photore sist Developer.
- C&D SEMICONDUCTOR 8826PC/8836HPO 3-Track Photore sist Coater.
- C&D SEMICONDUCTOR 8838VP Vapor Prime Tool.
- PERKIN-ELMER Micralign 552HTR Projection Mask Aligner.
- PERKIN-ELMER Micralign 552 Projection Mask Aligner.

PLASMA PROCESSING
- LAM 4420B Poly/Nitride Plasma Etcher.
- GASONICS L3510 Downstream Photore sist Stripper.
- GASONICS Aura 1000 Downstream Photore sist Stripper.
- MARCH AP 1000 Plasma Cleaning System, NEW.
- APPLIED MATERIALS P-5000 Plasma Etchers.
- (4) APPLIED MATERIALS 8330 and 8110 Plasma Etchers.
- METROLINE/IPC 9204 Plasma Barrel Stripper, NEW.
- (2) BRANSON/IPC 9104 Plasma Barrel Strippers.
- (3) BRANSON/IPC P-2100 Plasma Barrel Strippers.

A 10% BUYER’S PREMIUM APPLIES TO ALL ON-SITE PURCHASES
**WET PROCESSING**

- SEMITOOL Equinox 4-Head Wafer Plater.
- SEMITOOL Equinox Single-Head Wafer Plater.
- FSI Mercury Spray Acid Tool.
- UNIVERSAL PLASTICS/AKRION UP-V2 Solvent and Acid Wet Stations, w/robotics, NEW.
- REYNOLDS TECH LCD-25-PVDF Auto Gold Etch Tool.
- REYNOLDS TECH LCD-25-PVDF Auto Chrome Etch Tool.
- VERTEQ 1600-55 Spin Rinser Dryers, numerous.

**DEPOSITION**

1. (2) STS Multiplex CVD PECVD Tools, NEW.
2. VEECO/ION TECH Spectrion 3-Target Ion-Assisted PVD Tool.
3. EDDY C36A E-Beam Evaporator.
4. SPINNERED FILMS 18" PVD Tool.
5. VARIAN 3190 and 3180 PVD Tools.
6. VARIAN 160-10 Ion Implanter.
7. (2) ALCATEL ASM180T Leak Detectors.
8. VEECO MSS50 Leak Detector.

**THERMAL PROCESSING**

1. (4) MRL Coyote 430, 8", 4-tube, LPCVD, (1) Oxidation.
2. TEMPRESS 81103, 8", 3-tube, LPCVD Furnace.
3. AG ASSOCIATES 4108 Rapid Thermal Processor.
4. AG ASSOCIATES 4100 Rapid Thermal Processor.
5. AG ASSOCIATED 610 Rapid Thermal Processor.
6. (3) BRUCE BDF-41 Diffusion Furnaces.
7. (2) BRUCE BDF-4 Diffusion Furnaces.
8. (3) BRUCE BDF-8 Diffusion Furnaces.
**METROLOGY/INSPECTION**

- KLA/TENCOR S200 Overlay Registration Tool.
- KLA/TENCOR Surfscan 6220 Wafer Inspection Tool.
- KLA/TENCOR Surfscan 7700 Wafer Inspection Tool.
- KLA/TENCOR P-10 Profilometer.
- KLA/TENCOR Omnimap NCI 10.
- NANOMETRICS Nanospec/AFT 9100 Film Thickness Measurement Tool.
- (2) NANOMETRICS Nanospec/AFT 4000 Film Thickness Measurement Tools.
- (2) NANOMETRICS Nanospec/AFT 2100UV Film Thickness Measurement Tools.
- Sci Film Tek 4000-A Reflectometer, NEW.
- FLEXUS 2320I Film Stress Tester.
- FSM Film Stress Tester.

- (4) ZEISS Axiotron Microscopes.
- (2) ZEISS Universal Microscopes.
- NIKON Optiphot 66 Nomarski Microscope.
- (20) NIKON Optiphot 66 Microscopes.
- NIKON Metaphot Microscope.
- WILD MB, M420 Stereo Microscopes.
- LEITZ Miniload 2 Microhardness Tester.

**LASERS**

- EO TECHNICS CSM2000 Laser Wafer Marker.
- LUMONICS Lightwriter WAMS-50 Laser Marking Tool.
- (6) ESI 80 Laser Memory Repair Tools.
- AOI FX 5050 Fiber Optics Laser Welder, w/NEC FX-1801 Laser.

**SOME ITEMS SUBJECT TO PRIOR SALE**
ASSEMBLY

(1) K&S 1488L Turbo Plus Ball Bonders.
(3) K&S 1419-3 Ball Bonders.
(22) KAIJO FB-118A Ball Bonders.
(4) ESEC 3018 Ball Bonders.
(2) ASYMTEK Millennium Glue Dispensers.
(2) LAURIER DS-4000 Speed Star Pick and Place Tools.
(4) LAURIER DS-3000 Pick-and-Place Tools.
SEMICONDUCTOR EQUIPMENT CORP.
860 Eutectic Die Bonder.
DISCO DAD-321 Dicing Saw.
DISCO DFD 5/8 Dual-Spindle Dicing Saw.
ASSEMBLY TECHNOLOGIES 1100 Dicing Saw.
TECA-PRINT ICS2300 Auto Pad Printer.
TECA-PRINT ICS2200 Auto Pad Printer.
(2) FICO TF12A Auto Trim and Form Presses.
SEMICONDUCTOR TECHNOLOGIES 4070 Lead Inspection Tool.
VIKING 1042 Pick and Place Tool.
DYNATEX GST-150 Wafer Scribe/Breaker.
(3) DYNATEX DX-III Wafer Scribe/Breakers.
LOOMIS 38LD Wafer Scribe.

LAURIER DS-4000 SPEED STAR PICK & PLACE TOOL

DYNATEX DX-3 WAFER SCRIBER/BREAKER

SEC 860 EUTECTIC DIE BONDER

LAURIER DS-3000 PICK & PLACE TOOL

DYNATEX GST-150 WAFER SCRIBER/BREAKER

K&S 8028 AUTO WIRE BONDER

K&S 982-2 DICING SAW
AUTOMATIC TEST EQUIPMENT

(2) LTX Fusion System on Chip Testers.
(2) TERADYNE A580 Analog Testers.
(2) LTX Synchronmaster HT Testers.
(5) ADVANTEST T3340 Memory Testers.
ELECTROGLAS 4090u Prober.
(2) ELECTROGLAS 2001 CXE Probers.
ELECTROGLAS 2001 X Prober.

ENVIRONMENTAL

(2) THERMOTRON SE-600-3-3 Temperature Chambers, NEW.
(2) THERMOTRON SE-600-5-5 Temperature Chambers, NEW.

INSTRUMENTATION

HEWLETT-PACKARD and TEKTRONIX Oscilloscopes, Power Supplies and Analyzers.
(2) AGILENT B6142B Optical Spectrum Analyzers, NEW.
(8) AGILENT B6141B Optical Spectrum Analyzers, NEW.
(5) AGILENT B6140B Optical Spectrum Analyzers, NEW.
(2) HEWLETT-PACKARD 70951B Optical Spectrum Analyzers.

POLISHING

(4) LOGITECH PM528 Wafer Polishers.
LOGITECH PM4 Wafer Polisher.
LOGITECH IWBT2 Wafer Substrate Bonder.
CRANE Lapmaster 12 Polishing Machine.

MICAL FOX

TENNEY & BLUE M ENVIRONMENTAL CHAMBERS

TENNEY JR. TEMP. CHAMBERS

BUEHLER FIBRPOL POLISHERS

LOGITECH IWBT2 WAFER BONDER

ENVIRONMENTAL CHAMBERS

LOGITECH IWBT2 WAFER BONDER

LOGITECH IWBT2 WAFER BONDER

LOGITECH IWBT2 WAFER BONDER

LOGITECH IWBT2 WAFER BONDER

LOGITECH IWBT2 WAFER BONDER
**INTERNATIONAL LOCATIONS TO BE SOLD BY VIDEO FROM READING, PA SITE**

- **SINGAPORE**
  - (14) K&S 1488L Turbo Plus Wire Bonders, w/K&S 2929 HS, 870 PRS REV.1, 65-0-0-08, 7-11-9-04A OPERATING SYSTEM.
  - (2) SEMITOOL 8705 Spin Rinse Dryers.
  - SEMITOOL 8300 Spin Rinse Dryer.
  - Custom-Made Machined Mold Press Components.
  - (4) ESEC 3018 Wire Bonders.
  - EO TECHNICS CSM 2000 Laser Wafer Marker.
  - ICE ST Trim and Form Press.
  - (2) FICO TFM2A Trim and Form Presses.
  - (2) LTX SYNCHROMASTER-HT Testers, w/Sparc Ultra NIC upgrades.
  - (2) ASECO S-170-D IC Handlers.
  - (20) K&S 1488L Turbo Plus Wire Bonders, w/Flex Line III MATERIAL HANDLING SYSTEM.
  - TECA-PRINT ICS-2300 Pad Printer.
  - TECA-PRINT ICS-2200 Pad Printer.

- **BANGKOK, THAILAND**
  - (3) AETRIUM 5050 IC Handlers.
  - (2) AETRIUM 4098 Handlers.
  - (2) ASECO S-150 Handlers.
  - TRIGON Sigma 101NS IC Handler.
  - TRIGON Sigma 102NS IC Handler.
  - (2) TRIGON Sigma 101 IC Handlers.
  - (4) ADVANTEST T3340 Memory Testers.
  - (22) KAIJO FB-118A Wire Bonders.
  - (5) DELTA DESIGN 1210 Ovens.
  - BLUE M ELECTRIC MP-256RY-HP Oven, s/n Y10E223515YE.
  - BLUE M ELECTRIC DCA-256CY Oven, s/n DC4699.
  - (2) BLUE M ELECTRIC MP-1406KY Ovens.
  - (2) BLUE M ELECTRIC MP-246-EY Ovens.
  - BLUE M ELECTRIC MP-246SRY Ovens.
  - KELVINATOR UC109-2 Low Temperature Freezer.
  - SANYO MDF-435 Industrial Freezer.
  - (3) OLYMPUS SZ40 Microscopes.
  - OLYMPUS SZ30 Microscopes.
  - (3) KINERGY Robotic Lead Frame Loaders.
  - (2) RVI SYSTEMATION ST-50 Tape and Reel Machines, s/n's 75110, 7590.
  - (4) FUJI ELECTRIC FDP-723M RF Preheaters.
  - EVER TECHNOLOGIES FP-330A BOFP Lead Conditioning, s/n ETS-A780.
  - (3) AST 960 Marking Machines.
  - AMERICAN TECH MANUFACTURING AT-1045FP Lead Conditioning Tool.
  - ICE SP-ST Auto Trim and Form Press.
  - (2) DUSAN 5500 Presses.
  - (2) ICE SP-ST Manual Trim and Form Presses.
  - KAI N WAH Hydraulic Press System.

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LEASING INFORMATION
PRE-APPROVED LEASE/FINANCE CREDIT LINE AVAILABLE
In order to establish a lease/finance credit line for qualified purchasers that can be used for purchases at this or future Michael Fox International auctions, please contact...
Horizon-Keystone Leasing Services
John Messersmith
Phone (800) 514-2323 • Fax (800) 606-0037

The auction bidder must provide Michael Fox International, Inc. with a letter from the lease/finance company in the following format: The lease finance company ________ guarantees payment to Michael Fox International, Inc. on a non-contingent basis for purchases at the auction held at Agere Systems on Wednesday and Thursday, November 13 and 14.

INFORMATION PROVIDED IS BELIEVED TO BE ACCURATE, BUT IS NOT GUARANTEED